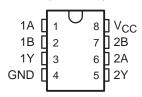
SLRS024 - DECEMBER 1976 - REVISED MAY 1990

PERIPHERAL DRIVERS FOR HIGH-VOLTAGE HIGH-CURRENT DRIVER APPLICATIONS

- Characterized for Use to 300 mA
- High-Voltage Outputs
- No Output Latch-Up at 55 V (After Conducting 300 mA)
- Medium-Speed Switching
- Circuit Flexibility for Varied Applications and Choice of Logic Function
- TTL-Compatible Diode-Clamped Inputs
- Standard Supply Voltages
- Plastic DIP (P) With Copper Lead Frame Provides Cooler Operation and Improved Reliability

D OR P PACKAGE (TOP VIEW)



SUMMARY OF SERIES SN75471

	DEVICE	LOGIC OF COMPLETE CIRCUIT	PACKAGES
l	SN75471	AND	D, P
ı	SN75472	NAND	D, P
ı	SN75473	OR	D, P

description

Series SN75471 dual peripheral drivers are functionally interchangeable with series SN75451B and series SN75461 peripheral drivers, but are designed for use in systems that require higher breakdown voltages than either of those series can provide at the expense of slightly slower switching speeds than series 75451B (limits are the same as series SN75461). Typical applications include high-speed logic buffers, power drivers, relay drivers, lamp drivers, MOS drivers, line drivers, and memory drivers.

The SN75471, SN75472, and SN75473 are dual peripheral AND, NAND, and OR drivers, respectively, (assuming positive logic), with the output of the logic gates internally connected to the bases of the npn output transistors.

Series SN75471 drivers are characterized for operation from 0°C to 70°C.



SN75471 THRU SN75473 DUAL PERIPHERAL DRIVERS

SLRS024 - DECEMBER 1976 - REVISED MAY 1990

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)

Supply voltage, V _{CC} (see Note 1)	7 V
Input voltage, V _I	5.5 V
Inter-emitter voltage (see Note 2)	5.5 V
Off-state output voltage, V _O	70 V
Continuous collector or output current (see Note 3)	400 mA
Peak collector or output current ($t_W \le 10$ ms, duty cycle $\le 50\%$, see Note 3)	500 mA
Continuous total power dissipation	See Dissipation Rating Table
Operating free-air temperature range, T _A	0°C to 70°C
Storage temperature range, T _{stq}	
Lead temperature 1,6 mm (1/16 inch) from case for 10 seconds	260°C

- NOTES: 1. Voltage values are with respect to the network GND, unless otherwise specified.
 - 2. This is the voltage between two emitters, A and B.
 - 3. Both halves of these dual circuits may conduct rated current simultaneously; however, power dissipation averaged over a short time interval must fall within the continuous dissipation rating.

DISSIPATION RATING TABLE

PACKAGE T _A ≤ 25°C POWER RATIN		DERATING FACTOR ABOVE T _A = 25°C	T _A = 70°C POWER RATING
D	725 mW	5.8 mW/°C	464 mW
Р	1000 mW	8.0 mW/°C	640 mW

recommended operating conditions

	MIN	NOM	MAX	UNIT
Supply voltage, V _{CC}	4.75	5	5.25	V
High-level input voltage, VIH	2			V
Low-level input voltage, V _{IL}			0.8	V
Operating free-air temperature, T _A	0		70	°C



logic symbol†

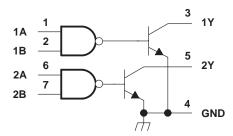
1A $\frac{1}{2}$ & \bigcirc 1Y 2A $\frac{6}{7}$ 2B $\frac{5}{2}$ 2Y

SN75471 FUNCTION TABLE (each driver)

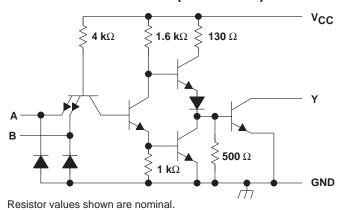
Α	В	Y
L	L	L (on state)
L	Н	L (on state)
Н	L	L (on state)
Н	Н	H (off state)

positive logic: Y = AB or A + B

logic diagram (positive logic)



SN75471 schematic (each driver)



electrical characteristics over recommended operating free-air temperature range

	DARAMETER	TEST COMPLICATE	SN75471			
	PARAMETER	TEST CONDITIONS	MIN	TYP‡	MAX	UNIT
VIK	Input clamp voltage	$V_{CC} = 4.75 \text{ V}, I_{I} = -12 \text{ mA}$		-1.2	-1.5	V
loH	High-level output current	$V_{CC} = 4.75 \text{ V}, V_{IH} = 2 \text{ V}, V_{OH} = 70 \text{ V}$			100	μΑ
V/01	Low-level output voltage	$V_{CC} = 4.75 \text{ V}, V_{IL} = 0.8 \text{ V}, I_{OL} = 100 \text{ mA}$		0.25	0.4	٧
VOL		$V_{CC} = 4.75 \text{ V}, V_{IL} = 0.8 \text{ V}, I_{OL} = 300 \text{ mA}$		0.5	0.7	
Ц	Input current at maximum input voltage	$V_{CC} = 5.25 \text{ V}, V_I = 5.5 \text{ V}$			1	mA
ΊΗ	High-level input current	$V_{CC} = 5.25 \text{ V}, V_I = 2.4 \text{ V}$			40	μΑ
Ι _Ι L	Low-level input current	$V_{CC} = 5.25 \text{ V}, V_I = 0.4 \text{ V}$		-1	-1.6	mA
ІССН	Supply current, outputs high	$V_{CC} = 5.25 \text{ V}, V_I = 5 \text{ V}$		7	11	mA
ICCL	Supply current, outputs low	$V_{CC} = 5.25 \text{ V}, V_{I} = 0$		52	65	mA

 $[\]ddagger$ All typical values are at $V_{CC} = 5 \text{ V}$, $T_A = 25^{\circ}\text{C}$.

switching characteristics, $V_{CC} = 5 \text{ V}$, $T_A = 25^{\circ}\text{C}$

	PARAMETER	TEST COL	UDITIONS	SN75471			UNIT
	PARAMETER	TEST CONDITIONS		MIN	TYP	MAX	UNIT
tPLH	Propagation delay time, low-to-high-level output				30	55	
tPHL	Propagation delay time, high-to-low-level output	l _O ≈ 200 mA,			25	40	20
tTLH	Transition time, low-to-high-level output	$R_L = 50 \Omega$,	See Figure 1		8	20	ns
tTHL	Transition time, high-to-low-level output]			10	20	
Vон	High-level output voltage after switching	V _S = 55 V, See Figure 2	$I_O \approx 300 \text{ mA},$	V _S -18		·	mV



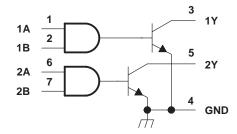
[†] This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

logic symbol[†]



†This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

logic diagram (positive logic)

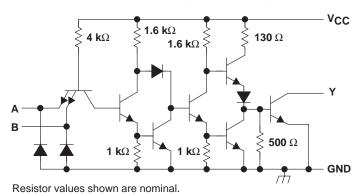


SN75472 FUNCTION TABLE (each driver)

Α	В	Υ
L	L	H (off state)
L	Н	H (off state)
Н	L	H (off state)
Н	Н	L (on state)

positive logic: $\underline{}$ Y = AB or A + B

SN75472 schematic (each driver)



electrical characteristics over recommended operating free-air temperature range

	PARAMETER	TEST CONDITIONS	SN75472			UNIT
	PARAMETER	TEST CONDITIONS	MIN	TYP‡	MAX	UNIT
VIK	Input clamp voltage	$V_{CC} = 4.75 \text{ V}, I_{I} = -12 \text{ mA}$		-1.2	-1.5	V
IOH	High-level output current	$V_{CC} = 4.75 \text{ V}, V_{IH} = 2 \text{ V}, V_{OH} = 70 \text{ V}$			100	μΑ
V/01	Low-level output voltage	$V_{CC} = 4.75 \text{ V}, V_{IL} = 0.8 \text{ V}, I_{OL} = 100 \text{ mA}$		0.25	0.4	V
VOL		$V_{CC} = 4.75 \text{ V}, V_{IL} = 0.8 \text{ V}, I_{OL} = 300 \text{ mA}$		0.5	0.7	V
Ц	Input current at maximum input voltage	$V_{CC} = 5.25 \text{ V}, V_{I} = 5.5 \text{ V}$			1	mA
ΊΗ	High-level input current	$V_{CC} = 5.25 \text{ V}, V_{I} = 2.4 \text{ V}$			40	μΑ
I _{IL}	Low-level input current	$V_{CC} = 5.25 \text{ V}, V_{I} = 0.4 \text{ V}$		-1	-1.6	mA
ICCH	Supply current, outputs high	$V_{CC} = 5.25 \text{ V}, V_{I} = 5 \text{ V}$		13	17	mA
ICCL	Supply current, outputs low	$V_{CC} = 5.25 \text{ V}, V_{I} = 0$		61	76	mA

 $[\]ddagger$ All typical values are at V_{CC} = 5 V, T_A = 25°C.

switching characteristics, $V_{CC} = 5 \text{ V}$, $T_A = 25^{\circ}\text{C}$

		TEST CO	NDITIONS	SN75472			UNIT
	PARAMETER	TEST CONDITIONS		MIN	TYP	MAX	UNIT
tPLH	Propagation delay time, low-to-high-level output				45	65	
tPHL	Propagation delay time, high-to-low-level output	I _O ≈ 200 mA,	C _L = 15 pF,		30	50	no
tTLH	Transition time, low-to-high-level output	$R_L = 50 \Omega$,	See Figure 1		13	25	ns
tTHL	Transition time, high-to-low-level output				10	20	
VOH	High-level output voltage after switching	V _S = 55 V, See Figure 2	IO ≈ 300 mA,	V _S -18			mV

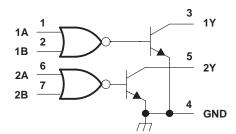


logic symbol†



[†]This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

logic diagram (positive logic)

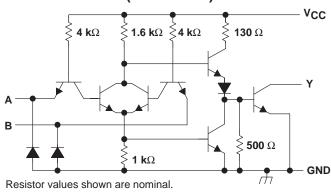


FUNCTION TABLE (each driver)

Α	В	Y
L	L	L (on state)
L	Н	H (off state)
Н	L	H (off state)
Н	Н	H (off state)

positive logic: $Y = A + B \text{ or } \overline{A} \overline{B}$

schematic (each driver)



electrical characteristics over recommended operating free-air temperature range

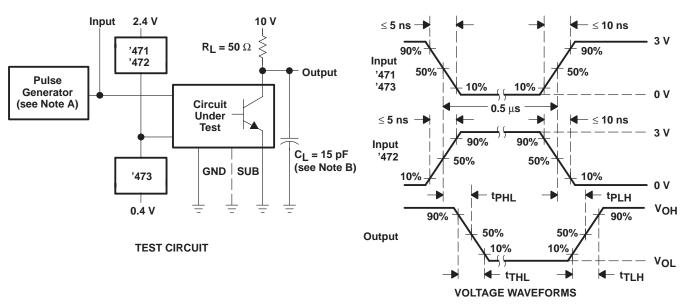
	DADAMETED	TEST CONDITIONS		SN75473		
	PARAMETER	TEST CONDITIONS	MIN	TYP [‡]	MAX	UNIT
٧ _{IK}	Input clamp voltage	$V_{CC} = 4.75 \text{ V}, I_{I} = -12 \text{ mA}$		-1.2	-1.5	V
IOH	High-level output current	$V_{CC} = 4.75 \text{ V}, V_{IH} = 2 \text{ V}, V_{OH} = 70 \text{ V}$			100	μΑ
\/o.	Low-level output voltage	$V_{CC} = 4.75 \text{ V}, V_{IL} = 0.8 \text{ V}, I_{OL} = 100 \text{ mA}$		0.25	0.4	V
VOL		$V_{CC} = 4.75 \text{ V}, V_{IL} = 0.8 \text{ V}, I_{OL} = 300 \text{ mA}$		0.5	0.7	V
Ц	Input current at maximum input voltage	$V_{CC} = 5.25 \text{ V}, V_I = 5.5 \text{ V}$			1	mA
ΊΗ	High-level input current	$V_{CC} = 5.25 \text{ V}, V_I = 2.4 \text{ V}$			40	μΑ
I _I L	Low-level input current	$V_{CC} = 5.25 \text{ V}, V_I = 0.4 \text{ V}$		-1	-1.6	mA
ICCH	Supply current, outputs high	$V_{CC} = 5.25 \text{ V}, V_{I} = 5 \text{ V}$		8	11	mA
ICCL	Supply current, outputs low	$V_{CC} = 5.25 \text{ V}, V_I = 0$		58	76	mA

 $[\]ddagger$ All typical values are at $V_{CC} = 5 \text{ V}$, $T_A = 25^{\circ}\text{C}$.

switching characteristics, $V_{CC} = 5 \text{ V}$, $T_A = 25^{\circ}\text{C}$

PARAMETER		TEST CONDITIONS		SN75473			UNIT
				MIN	TYP	MAX	UNII
^t PLH	Propagation delay time, low-to-high-level output				30	55	
tPHL	Propagation delay time, high-to-low-level output	I _O ≈ 200 mA,			25	40	
tTLH	Transition time, low-to-high-level output	$R_L = 50 \Omega$,			8	25	ns
tTHL	Transition time, high-to-low-level output]			10	25	
VOH	High-level output voltage after switching	V _S = 55 V, See Figure 2	$I_O \approx 300 \text{ mA},$	V _S -18			mV

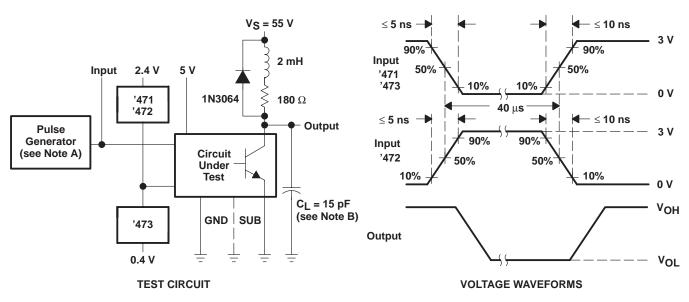
PARAMETER MEASUREMENT INFORMATION



NOTES: A. The pulse generator has the following characteristics: PRR \leq 1 MHz, $Z_{\mbox{\scriptsize O}}\approx$ 50 Ω

B. C_L includes probe and jig capacitance.

Figure 1. Switching Times



NOTES: A. The pulse generator has the following characteristics: PRR \leq 12.5 kHz, $Z_O\approx$ 50 Ω

B. C_L includes probe and jig capacitance.

Figure 2. Latch-Up Test







i.com 12-Jan-2006

PACKAGING INFORMATION

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Packag Qty	e Eco Plan ⁽²⁾ I	_ead/Ball Finisl	h MSL Peak Temp ⁽³⁾
SN75471D	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN75471DE4	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN75471DR	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN75471DRE4	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN75471P	ACTIVE	PDIP	Р	8	50	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN75471PE4	ACTIVE	PDIP	Р	8	50	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN75472D	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN75472DE4	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN75472P	ACTIVE	PDIP	Р	8	50	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN75472PE4	ACTIVE	PDIP	Р	8	50	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN75473D	OBSOLETE	SOIC	D	8		TBD	Call TI	Call TI
SN75473P	OBSOLETE	PDIP	Р	8		TBD	Call TI	Call TI

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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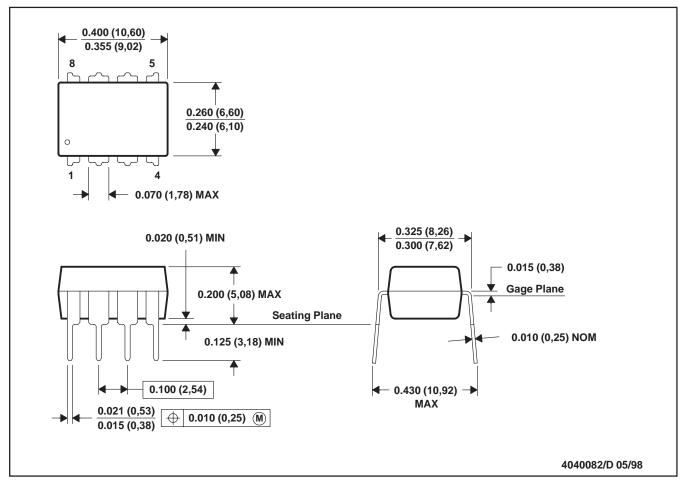


PACKAGE OPTION ADDENDUM

www.ti.com	12-Jan-2006
to Customer on an annual basis.	

P (R-PDIP-T8)

PLASTIC DUAL-IN-LINE



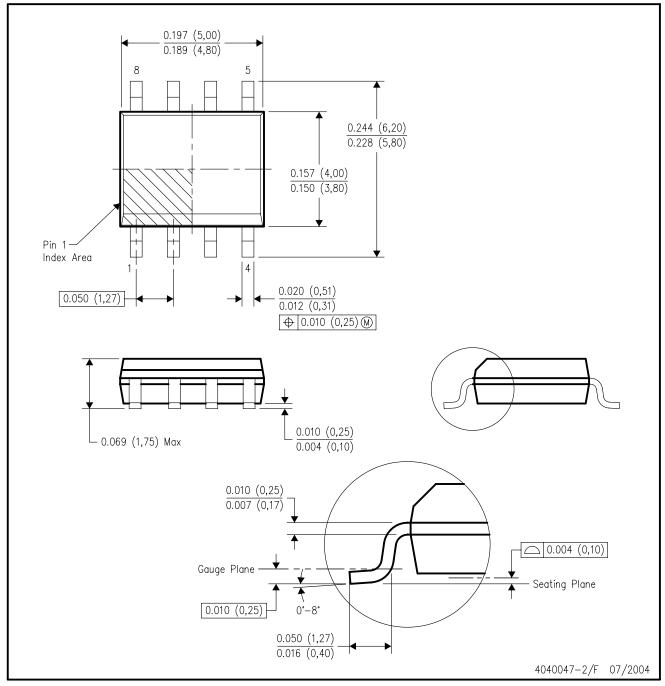
NOTES: A. All linear dimensions are in inches (millimeters).

- B. This drawing is subject to change without notice.
- C. Falls within JEDEC MS-001

For the latest package information, go to $http://www.ti.com/sc/docs/package/pkg_info.htm$

D (R-PDSO-G8)

PLASTIC SMALL-OUTLINE PACKAGE



NOTES:

- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).
- D. Falls within JEDEC MS-012 variation AA.



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